

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) A glass for a window of a semiconductor package, which is for use as a window material for a semiconductor package made of a plastic and has an average linear expansion coefficient of  $120 \times 10^{-7}/^{\circ}\text{C}$  to  $180 \times 10^{-7}/^{\circ}\text{C}$  at a temperature of 100 to  $300^{\circ}\text{C}$ .

2. (original) A glass for a window of a semiconductor package, having an average linear expansion coefficient of  $120 \times 10^{-7}/^{\circ}\text{C}$  to  $180 \times 10^{-7}/^{\circ}\text{C}$  at a temperature of 100 to  $300^{\circ}\text{C}$  and having a U content of 5 ppb or less and a Th content of 5 ppb or less.

3. (currently amended) The glass for a window for a semiconductor package as recited in claim 1 ~~or 2~~, which contains Cu and phosphorus oxide.

4. (original) The glass for a window of a semiconductor package as recited in claim 3, in which a wavelength which exhibits a transmittance of 50 % is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm.

5. (original) The glass for a window of a semiconductor package as recited in claim 3, which contains, by cationic %, 23 to 41 % of  $P^{5+}$ , 4 to 16 % of  $Al^{3+}$ , 11 to 40 % of  $Li^{+}$ , 3 to 13 % of  $Na^{+}$ , 12 to 53 % of  $R^{2+}$  ( $R^{2+}$  stands for  $Mg^{2+}$ ,  $Ca^{2+}$ ,  $Sr^{2+}$ ,  $Ba^{2+}$  or  $Zn^{2+}$ ) and 2.6 to 4.7 % of  $Cu^{2+}$  and contains  $F^{-}$  and  $O^{2-}$  as anionic components.

6. (currently amended) The glass window for a semiconductor package, which is made of the glass for a window recited in claim 1 ~~or~~ 2.

7. (original) A glass window for a semiconductor package, having a lens function and having an average linear expansion coefficient of  $120 \times 10^{-7}/^{\circ}C$  to  $180 \times 10^{-7}/^{\circ}C$  at a temperature of 100 to  $300^{\circ}C$ .

8. (original) A glass window for a semiconductor package, which is formed of a glass having an average linear expansion coefficient of  $120 \times 10^{-7}/^{\circ}C$  to  $180 \times 10^{-7}/^{\circ}C$  at a temperature of 100 to  $300^{\circ}C$ , having a U content of 5 ppb or less and a Th content of 5 ppb or less and containing Cu and phosphorus oxide, in which a wavelength which exhibits a transmittance of 50 % is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass window has a thickness of 0.5 mm.

9. (original) The glass window for a semiconductor package as recited in claim 6, which is a precision press-molded product.

10. (original) A process for the production of a glass window for a semiconductor package, which comprises precision-press-molding a lens-shaped window material glass made of a glass having an average linear expansion coefficient of  $120 \times 10^{-7}/^{\circ}\text{C}$  to  $180 \times 10^{-7}/^{\circ}\text{C}$  at a temperature of 100 to  $300^{\circ}\text{C}$ .

11. (original) A semiconductor package comprising the glass window for a semiconductor package recited in claim 6, a semiconductor device and a package encasing the semiconductor device, the glass window having an attaching portion made of a plastic material.

12. (original) A semiconductor package as recited in claim 11, wherein the semiconductor device is an image-sensing device.